

N-Channel Enhancement-Mode Vertical DMOS FET

Features

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{iss} and fast switching speeds
- Excellent thermal stability
- ► Integral source-drain diode
- High input impedance and high gain

Applications

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

Ordering Information

Part Number	Package Option	Packing
VN0109N3-G	TO-92	1000/Bag
VN0109N3-G P002		
VN0109N3-G P003		
VN0109N3-G P005	TO-92	2000/Reel
VN0109N3-G P013		
VN0109N3-G P014		

⁻G denotes a lead (Pb)-free / RoHS compliant package.

Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSS}
Drain-to-gate voltage	BV _{DGS}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Typical Thermal Resistance

Package	$oldsymbol{ heta}_{j_{oldsymbol{a}}}$
TO-92	132°C/W

General Description

This enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Product Summary

BV _{DSS} /BV _{DGS}	R _{DS(ON)} (max)	I _{DSS} (min)
90V	3.0Ω	2.0A

Pin Configuration



Product Marking



Package may or may not include the following marks: Si or

TO-92

Contact factory for Wafer / Die availablity.

Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

Thermal Characteristics

Package	l _D (continuous) [†]	I _D (pulsed)	Power Dissipation @T _c = 25°C	l _{DR} [†]	I _{DRM}	
TO-92	350mA	2.0A	1.0W	350mA	2.0A	

Notes:

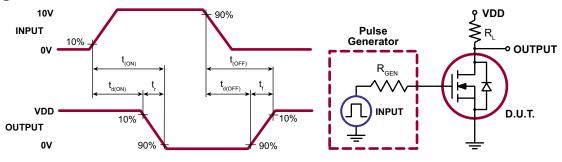
Electrical Characteristics (T_A = 25°C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions	
BV _{DSS}	Drain-to-source breakdown voltage	90	-	-	V	$V_{GS} = 0V, I_D = 1.0mA$	
$V_{\rm GS(th)}$	Gate threshold voltage	0.8	-	2.4	V	$V_{GS} = V_{DS}$, $I_D = 1.0 \text{mA}$	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with temperature	-	-3.8	-5.5	mV/°C	$V_{GS} = V_{DS}$, $I_D = 1.0 \text{mA}$	
I _{GSS}	Gate body leakage	-	ı	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
		_	-	1.0		$V_{GS} = 0V, V_{DS} = Max Rating$	
I _{DSS}	Zero gate voltage drain current	-	ı	100	μA	V_{DS} = 0.8 Max Rating, V_{GS} = 0V, T_{A} = 125°C	
ı	On state drain current	0.5	1.0	-	_	$V_{GS} = 5.0V, V_{DS} = 25V$	
I _{D(ON)}	On-state drain current	2.0	2.5	-	A	$V_{GS} = 10V, V_{DS} = 25V$	
D	Chatia duain to accurac an atata masiatanaa	-	3.0	5.0	0	$V_{GS} = 5.0V, I_{D} = 250mA$	
$R_{DS(ON)}$	Static drain-to-source on-state resistance		2.5	3.0	Ω	$V_{GS} = 10V, I_{D} = 1.0A$	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	-	0.70	1.0	%/°C	$V_{GS} = 10V, I_{D} = 1.0A$	
G _{FS}	Forward transductance	300	450	-	mmho	$V_{DS} = 25V, I_{D} = 500mA$	
C _{ISS}	Input capacitance	-	55	65		V _{GS} = 0V,	
C _{oss}	Common source output capacitance		20	25	pF	$V_{DS} = 25V$,	
C _{RSS}	Reverse transfer capacitance	-	5.0	8.0		f = 1.0MHz	
t _{d(ON)}	Turn-on delay time	-	3.0	5.0			
t _r	Rise time Turn-off delay time		5.0	8.0	ns	$V_{DD} = 25V,$	
t _{d(OFF)}			6.0	9.0		$I_D = 1.0A$, $R_{GEN} = 25\Omega$	
t _f	Fall time	-	5.0	8.0		GEN	
V _{SD}	Diode forward voltage drop	-	1.2	1.8	V	$V_{GS} = 0V, I_{SD} = 1.0A$	
t _{rr}	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V, I_{SD} = 1.0A$	

Notes:

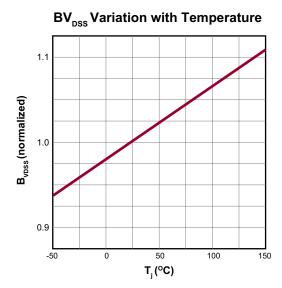
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

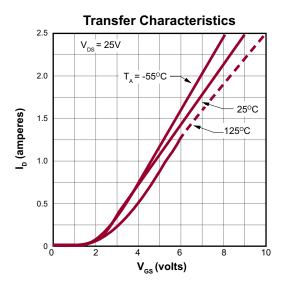
Switching Waveforms and Test Circuit

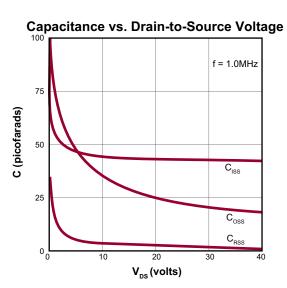


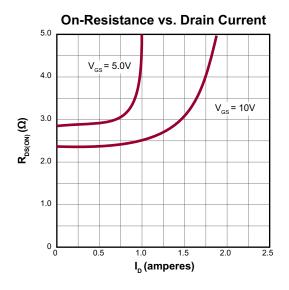
[†] I_D (continuous) is limited by max rated T_i .

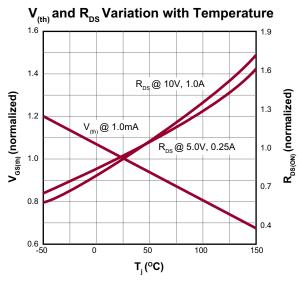
Typical Performance Curves

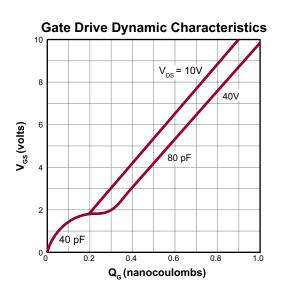




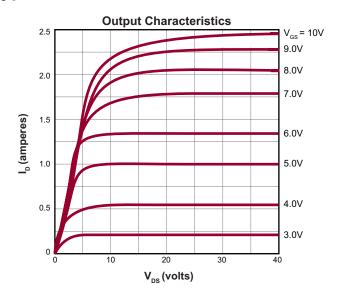


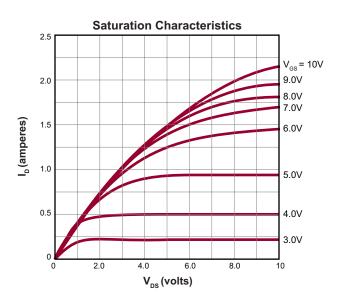


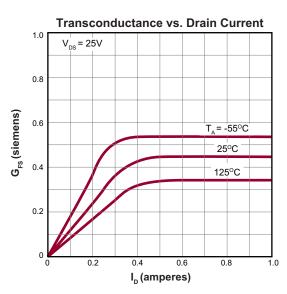


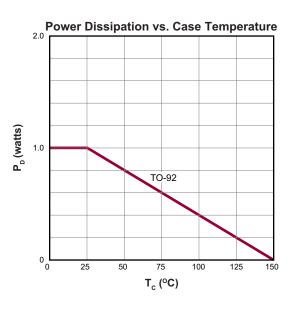


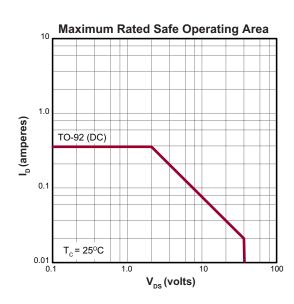
Typical Performance Curves (cont.)

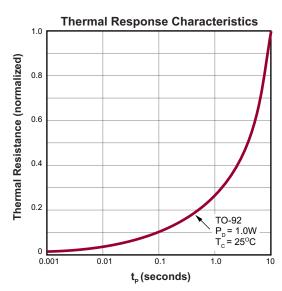




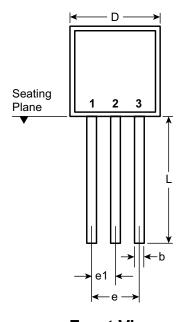


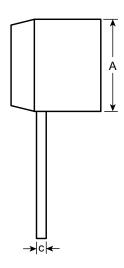






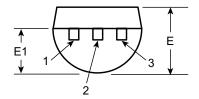
3-Lead TO-92 Package Outline (N3)





Front View

Side View



Bottom View

Symb	ol	Α	b	С	D	E	E1	е	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	1	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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^{*} This dimension is not specified in the JEDEC drawing.

[†] This dimension differs from the JEDEC drawing.